

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	44281	ceramic near1 substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/04/18 10:03
L2	551714	semiconductor near1 (package device)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/04/18 10:03
L3	523	1 near3 (aperture cavity cave)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/04/18 10:04
L4	139	2 and 3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/04/18 10:05
L5	39	4 and (bond\$3 near pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/04/18 10:05
L6	3	("5703397").URPN.	USPAT	OR	ON	2005/04/18 10:11
L7	11	("3916434" "4417392" "4827327" "4833102" "5018004" "5045639" "5095359" "5097318" "5122862" "5311402" "T105403").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/18 10:11
L8	50	5 6 7	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/18 10:11
L9	48	8 and ceramic	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/18 10:12
L10	31	9 and ((co adj fired) cofired sinter\$3 heating)	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/18 10:13